plastic shrink small outline package/transparent; 16 leads (straight leads); body width 4.4 mm

20 June 2016

Package information

1. Package summary

Terminal position codeD (double)Package type descriptive codeSSOP16TPackage type industry codeSSOP16T

Package style descriptive code SSOP (shrink small outline package)

Package body material type P (plastic)

Mounting method type S (surface mount)

Issue date 9-11-2001

Table 1. Package summary

Symbol	Parameter	Min	Тур	Nom	Max	Unit
D	package length	5.1	-	5.2	5.3	mm
E	package width	4.3	-	4.4	4.5	mm
A ₂	package height	1.1	-	1.2	1.3	mm
е	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	16	-	



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2. Package outline

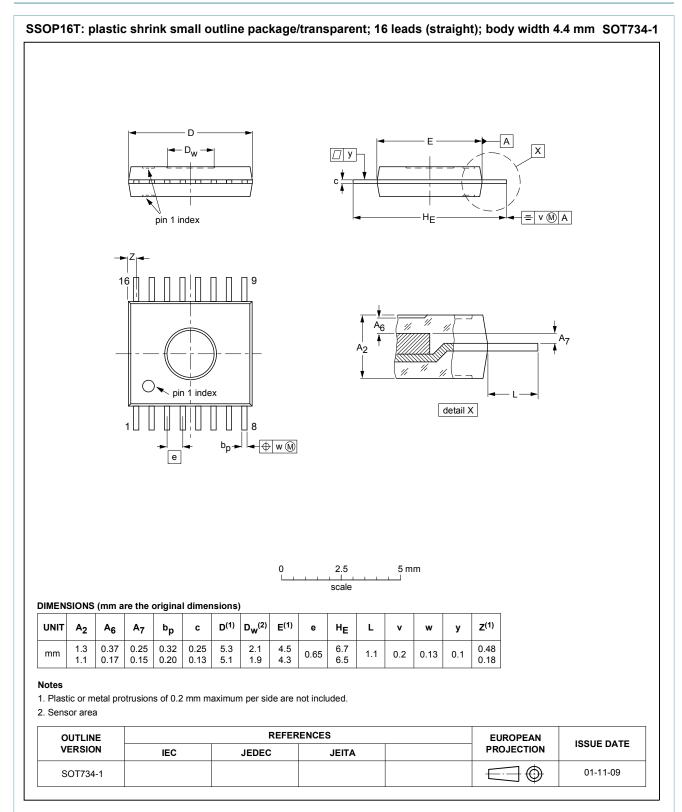
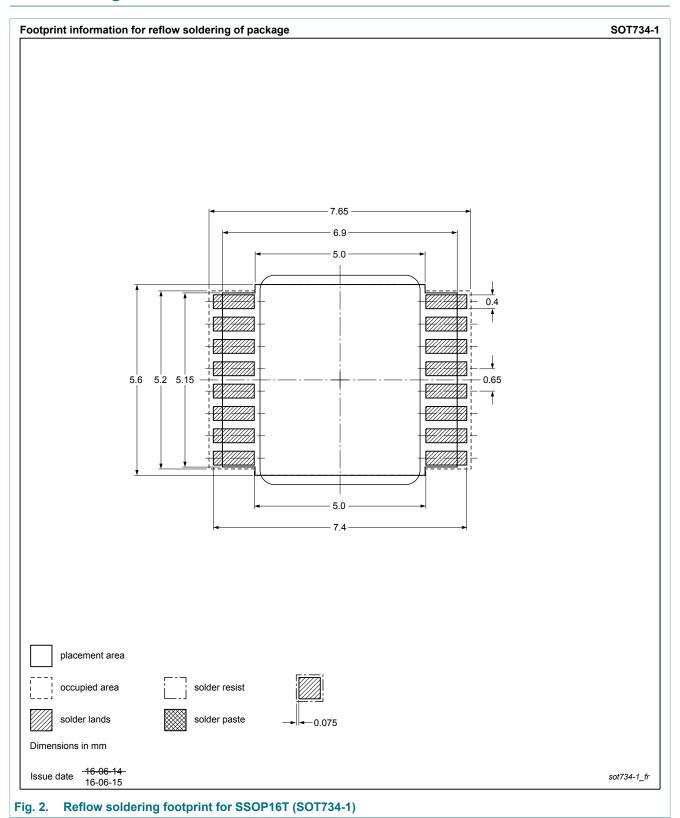


Fig. 1. Package outline SSOP16T (SOT734-1)

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3. Soldering



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4. Legal information

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plastic shrink small outline package/transparent; 16 leads (straight leads); body width 4.4 mm

5. Contents

1.	Package summary	.1
2.	Package outline	2
3.	Soldering	3
4.	Legal information	4

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5/5